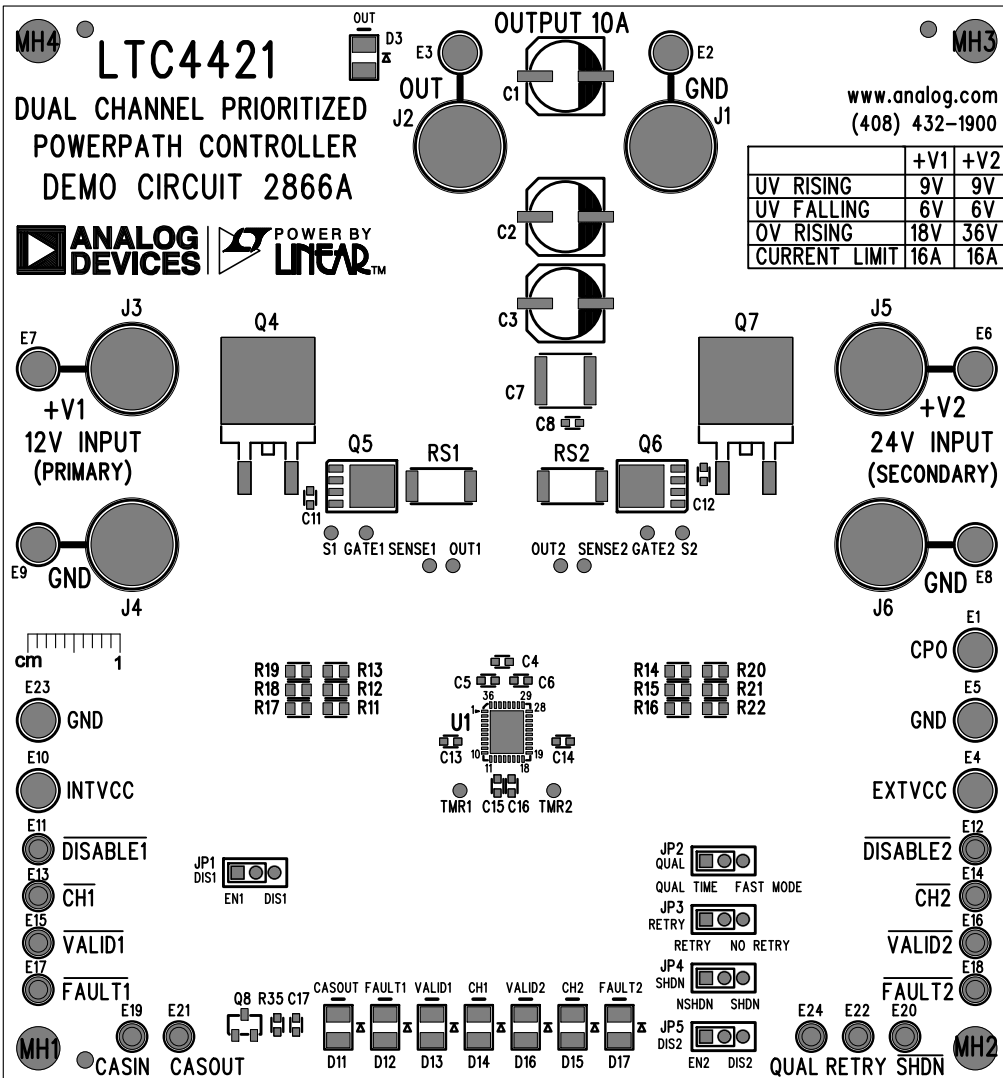
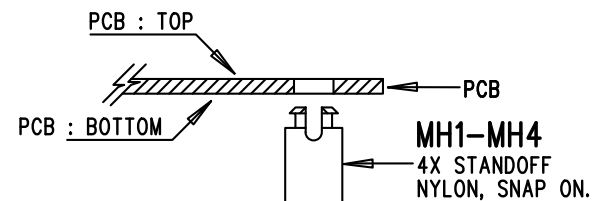




REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG. DATE
-	1	1ST PROTOTYPE	MANPREET S. 09-28-18

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN BELOW:



APPROVALS

PCB DES.	KIM T.
APP ENG.	MANPREET S.
SCALE = NONE	

 ANALOG DEVICES		 POWER BY LINEAR™		1630 McCARTHY BLVD. MILPITAS, CA 95035 TEL: (408)432-1900	
www.analog.com		www.linear.com			
TITLE: TOP ASSEMBLY DRAWING DUAL CHANNEL PRIORITIZED POWERPATH CONTROLLER					
SIZE N/A	IC NO. LTC4421IUE DEMO CIRCUIT 2866A				REV. 2
FILENAME: DC2866A-2.PCB				SHT 1 OF 2	